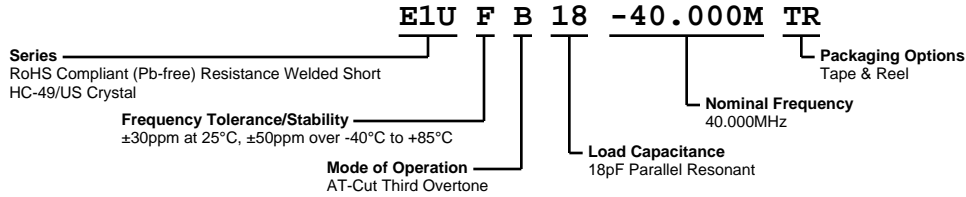


E1UFB18-40.000M TR



ECLIPTEK
CORPORATION



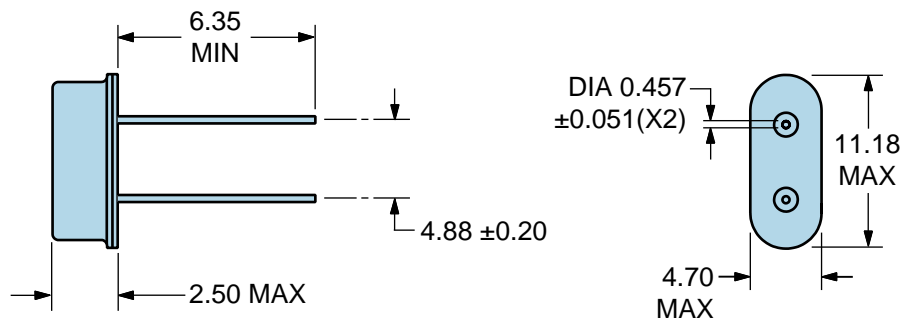
ELECTRICAL SPECIFICATIONS

Nominal Frequency	40.000MHz
Frequency Tolerance/Stability	$\pm 30\text{ppm}$ at 25°C , $\pm 50\text{ppm}$ over -40°C to $+85^\circ\text{C}$
Aging at 25°C	$\pm 5\text{ppm}/\text{year}$ Maximum
Load Capacitance	18pF Parallel Resonant
Shunt Capacitance (C0)	7pF Maximum
Equivalent Series Resistance	100 Ohms Maximum
Mode of Operation	AT-Cut Third Overtone
Drive Level	1mWatt Maximum
Storage Temperature Range	-40°C to $+125^\circ\text{C}$
Insulation Resistance	500 Megaohms Minimum at 100Vdc

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

Fine Leak Test	MIL-STD-883, Method 1014 Condition A
Gross Leak Test	MIL-STD-883, Method 1014 Condition C
Lead Integrity	MIL-STD-883, Method 2004
Lead Termination	Sn $2\mu\text{m}$ - $6\mu\text{m}$
Mechanical Shock	MIL-STD-202, Method 213 Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010
Vibration	MIL-STD-883, Method 2007 Condition A

MECHANICAL DIMENSIONS (all dimensions in millimeters)

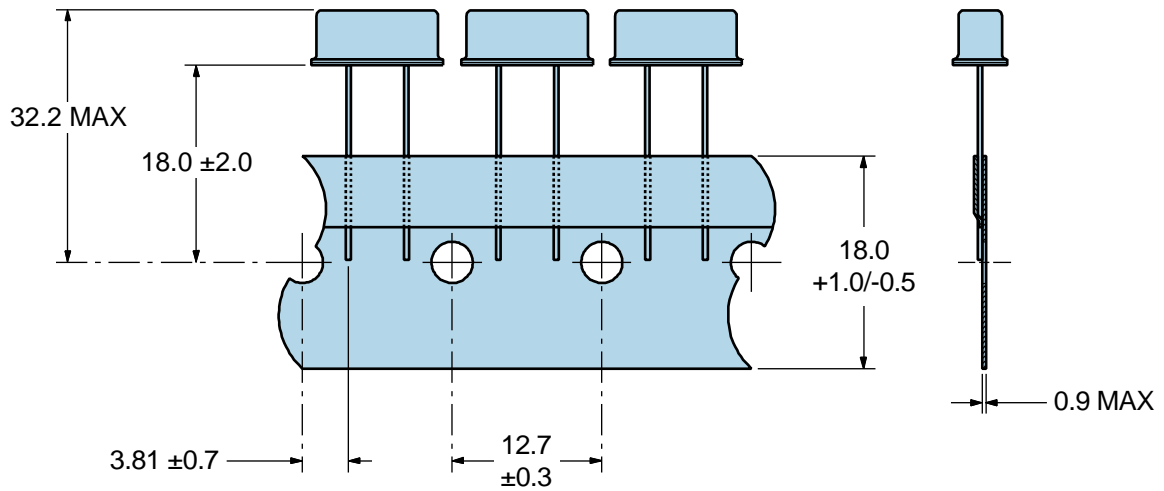


LINE	MARKING
1	E40.000M E=Eclipsek Designator M=MHz

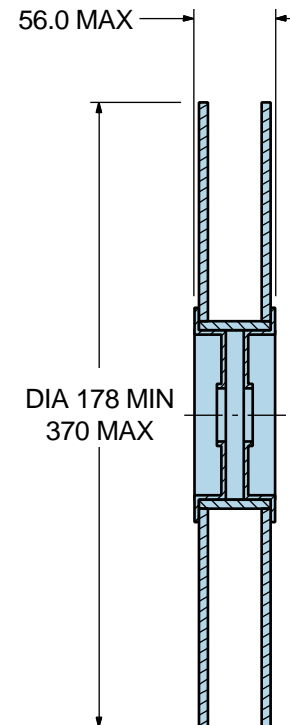
E1UFB18-40.000M TR

Tape & Reel Dimensions

Quantity Per Reel: 1,000 Pieces



*Compliant to EIA 468B



Recommended Solder Reflow Methods



High Temperature Solder Bath (Wave Solder)

$T_S\text{ MAX}$ to T_L (Ramp-up Rate) 3°C/second Maximum

Preheat

- Temperature Minimum ($T_S\text{ MIN}$) 150°C
- Temperature Typical ($T_S\text{ TYP}$) 175°C
- Temperature Maximum ($T_S\text{ MAX}$) 200°C
- Time ($t_s\text{ MIN}$) 60 - 180 Seconds

Ramp-up Rate (T_L to T_P) 3°C/second Maximum

Time Maintained Above:

- Temperature (T_L) 217°C
- Time (t_L) 60 - 150 Seconds

Peak Temperature (T_P) 260°C Maximum for 10 Seconds Maximum

Target Peak Temperature ($T_P\text{ Target}$) 250°C +0/-5°C

Time within 5°C of actual peak (t_p) 20 - 40 seconds

Ramp-down Rate 6°C/second Maximum

Time 25°C to Peak Temperature (t) 8 minutes Maximum

Moisture Sensitivity Level Level 1

Recommended Solder Reflow Methods



Low Temperature Solder Bath (Wave Solder)

T_s MAX to T_L (Ramp-up Rate)	5°C/second Maximum
Preheat	
- Temperature Minimum (T _s MIN)	N/A
- Temperature Typical (T _s TYP)	150°C
- Temperature Maximum (T _s MAX)	N/A
- Time (t _s MIN)	30 - 60 Seconds
Ramp-up Rate (T_L to T_P)	5°C/second Maximum
Time Maintained Above:	
- Temperature (T _L)	150°C
- Time (t _L)	200 Seconds Maximum
Peak Temperature (T_P)	245°C Maximum
Target Peak Temperature (T_P Target)	245°C Maximum 1 Time / 235°C Maximum 2 Times
Time within 5°C of actual peak (t_p)	5 seconds Maximum 1 Time / 15 seconds Maximum 2 Times
Ramp-down Rate	5°C/second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.